

Features:

- Higher power ratings than standard thick film chips
- Absolute TCRs to $\pm 100 \text{ ppm}/^\circ\text{C}$
- Impervious to Sulfur contamination, no silver present in terminations
- Absolute Tolerances to 1%
- Completely lead free and RoHS compliant without exemptions – does not use lead containing glass
- Comparable in cost to standard thick film chip resistors



Electrical Specifications

Type / Code	Package Type	Power Rating(2) (Watts) @ 70°C	Maximum Working Voltage(1)	Maximum Overload Voltage	Resistance Temperature Coefficient	Ohmic Range (Ω) and Tolerance
						1%, 5%
RNCP0402	0402	0.1W	50V	100V	$\pm 100 \text{ ppm}/^\circ\text{C}$	1 - 10K
RNCP0603	0603	0.125W	150V	300V	$\pm 100 \text{ ppm}/^\circ\text{C}$	1 - 47K
RNCP0805	0805	0.25W	200V	400V	$\pm 100 \text{ ppm}/^\circ\text{C}$	1 - 100K
RNCP1206	1206	0.5W	200V	400V	$\pm 100 \text{ ppm}/^\circ\text{C}$	1 - 100K

(1) Lesser of $\sqrt{\text{PR}}$ or maximum working voltage.

(2) Power rating for each package size is valid if ambient temp $\leq 80^\circ\text{C}$ and terminal temp $\leq 105^\circ\text{C}$.

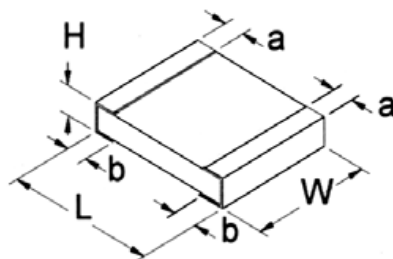
Please refer to the High Power Resistor Application Note (page 4) for more information on designing and implementing high power resistor types.

Performance Characteristics

Test	Test Conditions	Typical	
		1%	5%
Short Time Overload	RCWV * 2.5 or Max Overload Voltage, 5 seconds	$\pm 1\%$	$\pm 2\%$
Thermal Shock	MIL-STD-202F Method 107G -55°C to $+125^\circ\text{C}$, 1000 Cycles	$\pm 1\%$	$\pm 1\%$
Load Life	MIL-STD-202F Method 108A RCWV, 125°C , 1.5 Hrs ON, 0.5 Hrs OFF, Total 1000 Hrs	$\pm 2\%$	$\pm 3\%$
Humidity (steady state)	MIL-STD-202F Method 103B 85°C , 85% RH, RCWV 1.5Hrs ON, 0.5Hrs OFF, Total 1000Hrs	$\pm 3\%$	$\pm 3\%$
Resistance to Soldering Heat	MIL-STD-202F Method 210E $260 \pm 5^\circ\text{C}$, 10 ± 1 second	$\pm 1\%$	$\pm 1\%$

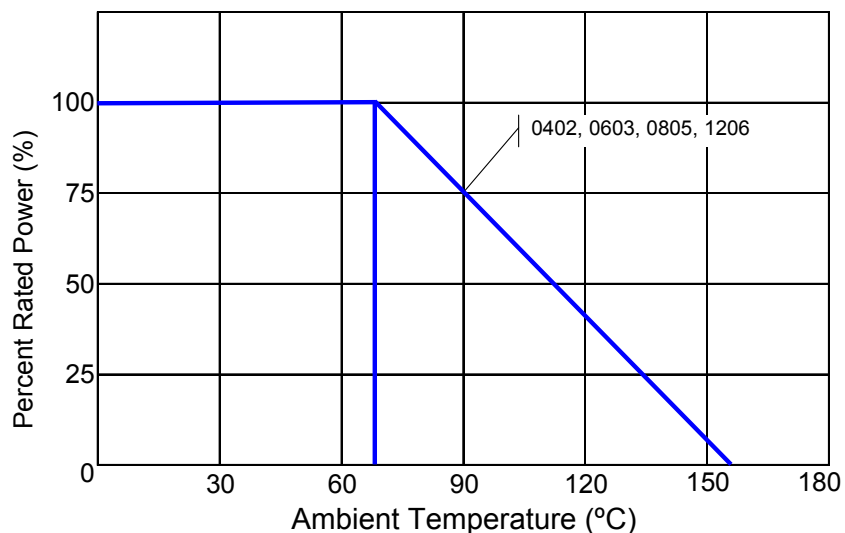
* Storage Temperature : $25 \pm 3^\circ\text{C}$; Humidity < 80% RH

Operating Temperature Range: -55°C to $+70^\circ\text{C}$. Above 70°C , the part should be derated linearly to zero power at 155°C .



Mechanical Specifications						
Type / Code	L Body Length	W Body Width	H Body Height	a Top Termination	b Bottom Termination	Unit
RNCP0402	0.040 ± 0.004 1.00 ± 0.10	0.02 ± 0.002 0.50 ± 0.05	0.012 ± 0.002 0.30 ± 0.05	0.01 ± 0.006 0.25 ± 0.15	0.012 ± 0.006 0.30 ± 0.15	inches mm
RNCP0603	0.059 ± 0.004 1.50 ± 0.20	0.032 ± 0.004 0.80 ± 0.10	0.016 ± 0.004 0.40 ± 0.10	0.012 ± 0.006 0.30 ± 0.15	0.016 ± 0.008 0.40 ± 0.20	inches mm
RNCP0805	0.079 ± 0.006 2.00 ± 0.15	0.049 ± 0.006 1.25 ± 0.15	0.020 ± 0.004 0.50 ± 0.10	0.018 ± 0.008 0.40 ± 0.20	0.024 ± 0.008 0.60 ± 0.20	inches mm
RNCP1206	0.122 ± 0.008 3.10 ± 0.20	0.059 ± 0.008 1.50 ± 0.20	0.020 ± 0.004 0.50 ± 0.10	0.020 ± 0.012 0.50 ± 0.20	0.028 ± 0.008 0.70 ± 0.20	inches mm

Power Derating Curve:



RNCP Series

High Power Anti-Sulfur Thin Film Chip Resistor

Stackpole Electronics, Inc.

Resistive Product Solutions

How to Order

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
R	N	C	P	0	6	0	3	F	T	D	4	K	7	5
Product Series		Size	Power	Tolerance			Packaging				TCR		Resistance Value	
RNCP	High Power Anti-Corrosive	0402	0.1W	Code	Tol	Value	Code	Description	Size	Quantity	Code	ppm	Four characters with the multiplier used as the decimal holder. 1 ohm = 1R00 47 Kohm = 47K0 100 Kohm = 100K	
		0603	0.125W	F	1%	E94, E24	T	7" Reel - Paper Tape	0402	10,000	D	100		
		0805	0.25W	J	5%	E24			0603, 0805, 1206	5,000				
		1206	0.5W											

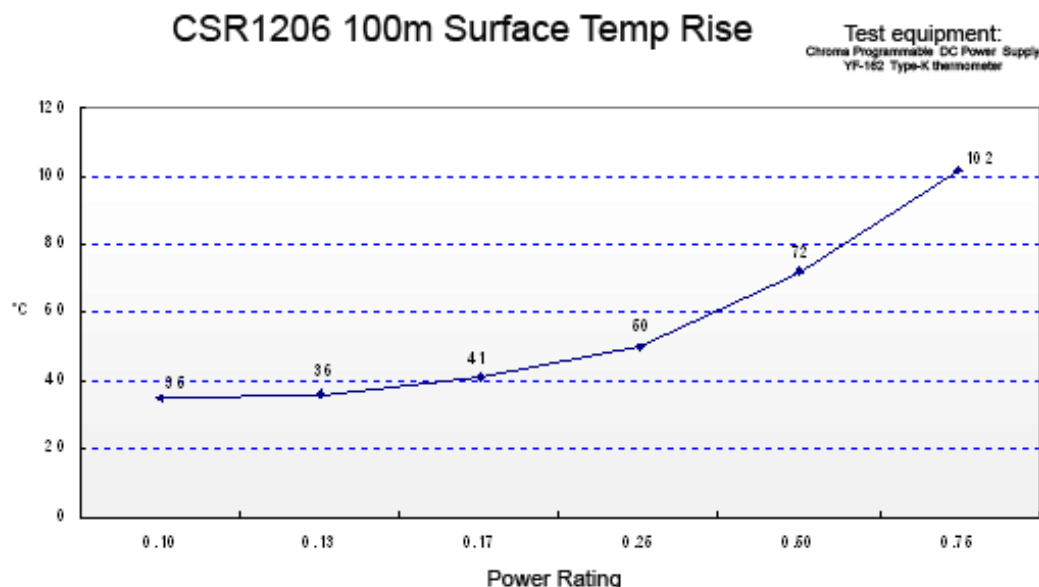
Legacy Part Number (before January 3, 2011):

SEI Type		Code			TCR	Nominal Resistance	Tolerance	Packaging				
RNCP		0603			T1	4.75K	1%	R				
Type	Description	Code	Wattage	Size	Code		Tol	Value	SEI Types	Pkg Qty	Description	Code
RNCP	High Power Anti-Corrosive	0402	0.1W	0402	T1 = 100ppm		1%	E94, E24	0402	10,000	7" reel - paper tape	R
		0603	0.125W	0603			5%	E24	0603, 0805, 1206	5,000		
		0805	0.25W	0805								
		1206	0.5W	1206								

High Power Chip Resistors and Thermal Management

Stackpole has developed several surface mount resistor series in addition to our current sense resistors, which have had higher power ratings than standard resistor chips. This has caused some uncertainty and even confusion by users as to how to reliably use these resistors at the higher power ratings in their designs.

The data sheets for the RHC, RMCP, RNCP, CSR, CSRN, CSRF, CSS, and CSSH state that the rated power assumes an ambient temperature of no more than 100 degrees C for the CSS / CSSH series and 70 degrees C for all other high power resistor series. In addition, IPC and UL best practices dictate that the combined temperature on any resistor due to power dissipated and ambient air shall be no more than 105C. At first glance this wouldn't seem too difficult, however the graph below shows typical heat rise for the CSR ½ 100 milliohm at full rated power. The heat rise for the RMCP and RNCP would be similar. The RHC with its unique materials, design, and processes would have less heat rise and therefore would be easier to implement for any given customer.



The 102 degrees C heat rise shown here would indicate there will be additional thermal reduction techniques needed to keep this part under 105C total hot spot temperature if this part is to be used at 0.75 watts of power. However, this same part at the usual power rating for this size would have a heat rise of around 72 degrees C. This additional heat rise may be dealt with using wider conductor traces, larger solder pads and land patterns under the solder mask, heavier copper in the conductors, vias through PCB, air movement, and heat sinks, among many other techniques. Because of the variety of methods customers can use to lower the effective heat rise of the circuit, resistor manufacturers simply specify power ratings with the limitations on ambient air temperature and total hot spot temperatures and leave the details of how to best accomplish this to the design engineers. Design guidelines for products in various market segments can vary widely so it would be unnecessarily constraining for a resistor manufacturer to recommend the use of any of these methods over another.

Note: The final resistance value can be affected by the board layout and assembly process, especially the size of the mounting pads and the amount of solder used. This is especially notable for resistance values ≤ 50 m Ω . This should be taken into account when designing.